NOTES:

1) Do not populate

Resonant Choke:
Ferrites ELP 18/10 NT 0062B2G (Top Layer)
Ferrites ELP 18/10 NT 0062B2G (Bottom Layer)
Airgap 0.1mm

Power Transformer:
Ferrites ELP 10/10 NT 0062B2G
Ferrites ELP 10/10 NT 0062B2G
Primary 2 windings, for aka 2041.1
Secondary 3x5 windings, for aka 2041.1

5V isolation voltage

Resonant Choke:
Ferritcore ELP 18/4/10 N87 B66283G (Top Layer)
Ferritcore ELP 18/2/10 N87 B66283G (Bottom Layer)

Power Transformer:
Ferritcore ELP 18/4/10 N87 B66283G
Ferritcore ELP 18/2/10 N87 B66283G
Primary: 2 windings, litz wire 20x0.1
Secondary: 2x5 windings, litz wire 20x0.1
Airgap 0.1mm

GND

4.75V...5.25V

Transformer *

Resonant Choke:
Ferritcore ELP 18/4/10 N87 B66283G (Top Layer)
Ferritcore ELP 18/2/10 N87 B66283G (Bottom Layer)

GND

7.5W Resonant converter: 5V 1.5A

Title:

Date: 12/02/2011
Drawn by M. Marjanovic

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